P-Channel Enhancement Mode Power MOSFET

MTA7D0P03H8

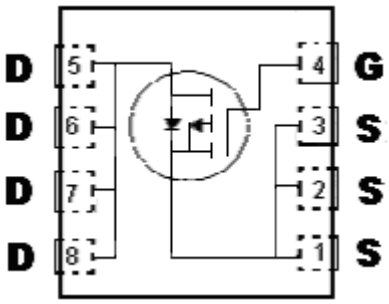
BV_{DSS}		-30V
I_D@V_{GS}=-10V, T_C=25°C		-55A
I_D@V_{GS}=-10V, T_A=25°C		-12.3A
$R_{DSON(TYP)}$	V_{GS}=-10V, I_D=-15A	7.1mΩ
	V_{GS}=-4.5V, I_D=-10A	9.3mΩ
	V_{GS}=-3V, I_D=-5A	14.3mΩ

Features

- Single Drive Requirement
- Low On-resistance
- Fast Switching Characteristic
- Pb-free lead plating and Halogen-free package

Symbol

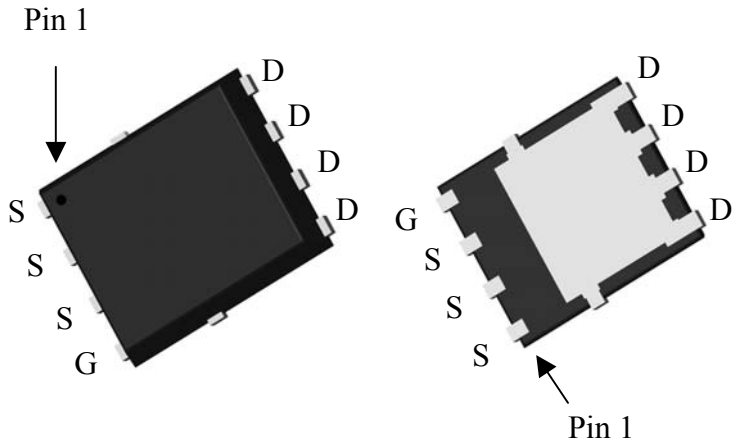
MTA7D0P03H8



G：Gate D：Drain S：Source

Outline

DFN5x6



Ordering Information

Device	Package	Shipping
MTA7D0P03H8-0-T6-G	DFN5x6 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T6 : 3000 pcs / tape & reel,13” reel

Product rank, zero for no rank products

Product name

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	10s	Steady State	Unit
Drain-Source Voltage		V_{DS}	-30		V
Gate-Source Voltage		V_{GS}	±20		
Continuous Drain Current @ T_C=25°C, V_{GS}=-10V (Note1)		I_D	-55		A
Continuous Drain Current @ T_C=100°C, V_{GS}=-10V (Note1)			-34.8		
Continuous Drain Current @ T_A=25°C, V_{GS}=-10V (Note2)		I_{DSM}	-17.4	-12.3	
Continuous Drain Current @ T_A=70°C, V_{GS}=-10V (Note2)			-13.9	-9.8	
Pulsed Drain Current (Note3)		I_{DM}	-180		
Avalanche Current @ L=0.1mH		I_{AS}	-59		
Avalanche Energy @ L=1mH, I_D=-24A, V_{DD}=-10V (Note4)		E_{AS}	288		mJ
Total Power Dissipation	T_C=25℃ (Note1)	P_D	50		W
	T_C=100℃ (Note1)		20		
	T_A=25°C (Note2)	P_{DSM}	5.0	2.5	
	T_A=70°C (Note2)		3.2	1.6	
Operating Junction and Storage Temperature Range		Tj, Tstg	-55~+150		°C

Thermal Data

Parameter		Symbol	Typical	Maximum	Unit
Thermal Resistance, Junction-to-case		$R_{th,j-c}$	2	2.5	°C/W
Thermal Resistance, Junction-to-ambient (Note2)	t≤10s	$R_{th,j-a}$	18	25	
	Steady State		45	50	

Note : 1.The power dissipation P_D is based on $T_{J(MAX)}$=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

2. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2 oz. copper, in a still air environment with T_A=25°C. The power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

3. Pulse width limited by junction temperature $T_{J(MAX)}$=150°C. Ratings are based on low frequency and low duty cycles to keep initial T_J=25°C.

4. 100% tested by conditions of L=100μH, I_{AS}=-10A, V_{GS}=-10V, V_{DD}=-15V

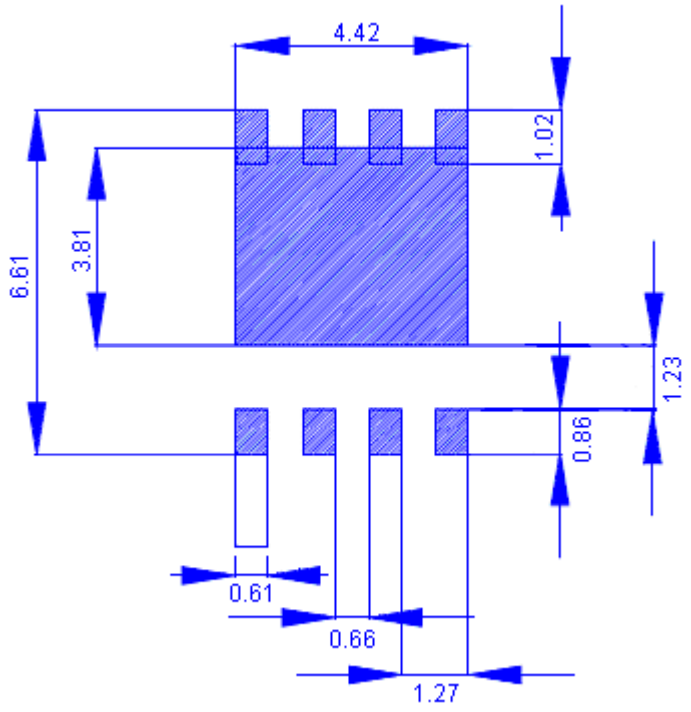
Characteristics (T_C=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	-30	-	-	V	V_{GS}=0V, I_D=-250μA
$V_{GS(th)}$	-0.8	-	-1.6		V_{DS} = V_{GS}, I_D=-250μA
G_{FS} *1	-	28.9	-	S	V_{DS} =-10V, I_D=-20A
I_{GSS}	-	-	±100	nA	V_{GS}=±20V, V_{DS}=0V
I_{DSS}	-	-	-1	μA	V_{DS} =-24V, V_{GS} =0V
	-	-	-25		V_{DS} =-24V, V_{GS} =0V, Tj=85°C

$R_{DS(ON)}$ *1	-	7.1	9.5	mΩ	V_{GS} =-10V, I_D=-15A
	-	9.3	16.5		V_{GS} =-4.5V, I_D=-10A
	-	14.3	23		V_{GS} =-3V, I_D=-5A
Dynamic *4					
Ciss	-	3763	-	pF	V_{DS}=-15V, V_{GS}=0V, f=1MHz
Coss	-	375	-		
Crss	-	318	-		
Qg *1, 2	-	77.7	117	nC	V_{DS}=-15V, V_{GS}=-10V, I_D=-15A
Qgs *1, 2	-	8.8	-		
Qgd *1, 2	-	14.8	-		
$t_{d(ON)}$ *1, 2	-	15.2	22.8	ns	V_{DS}=-15V, I_D=-15A, V_{GS}=-10V, R_G=1Ω
tr *1, 2	-	21.6	32.4		
$t_{d(OFF)}$ *1, 2	-	140.2	210.3		
t_f *1, 2	-	26.4	39.6		
Rg	-	4.5	-	Ω	f=1MHz
Source-Drain Diode					
V_{SD} *1	-	-0.82	-1.2	V	I_S=-10A, V_{GS}=0V
trr	-	17.9	-	ns	I_F=-10A, dI_F/dt=100A/μs
Qrr	-	12.2	-	nC	

Note : *1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%
*2.Independent of operating temperature
*3.Pulse width limited by maximum junction temperature.
*4.Guaranteed by design, not subject to production testing.

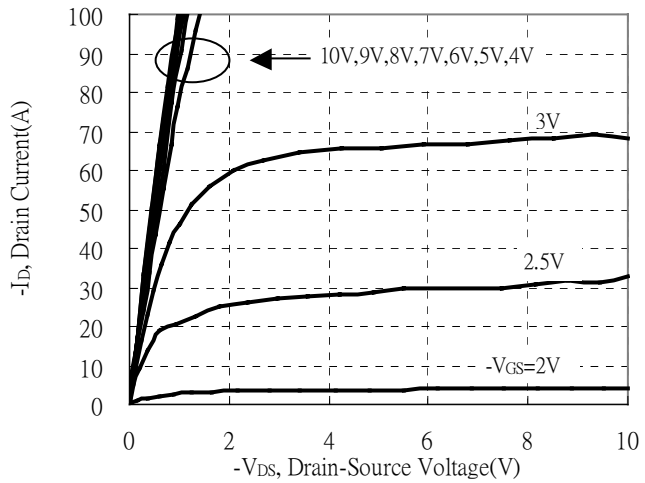
Recommended Soldering Footprint



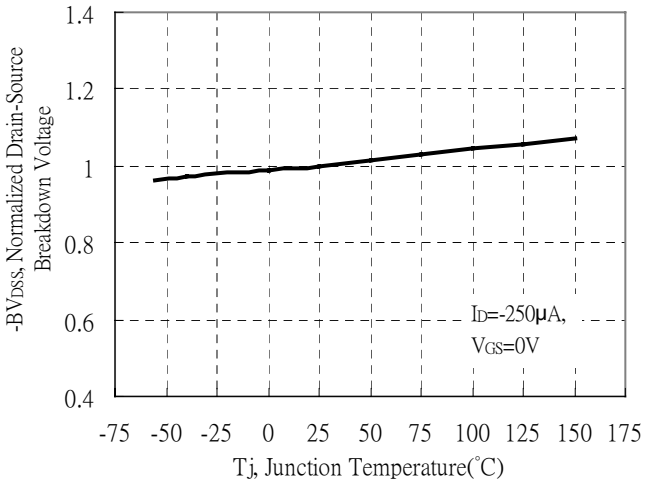
unit : mm

Typical Characteristics

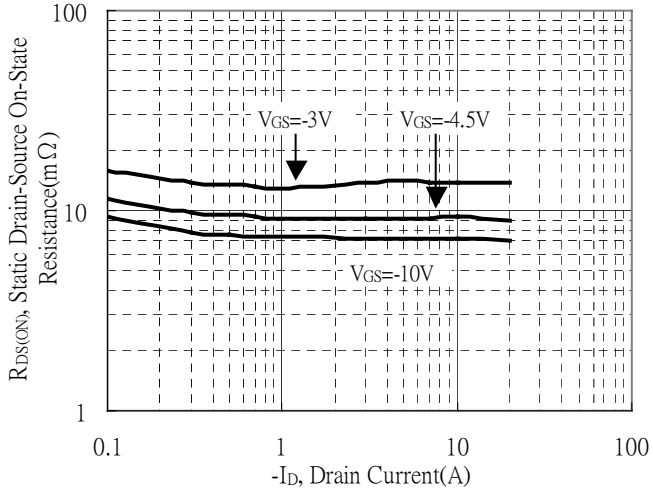
Typical Output Characteristics



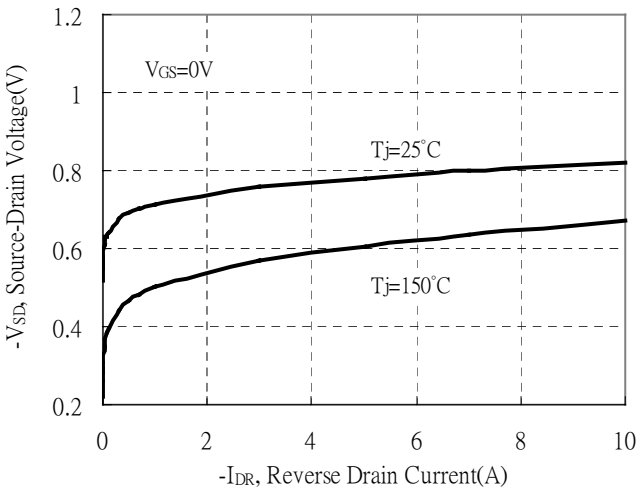
Brekdown Voltage vs Ambient Temperature



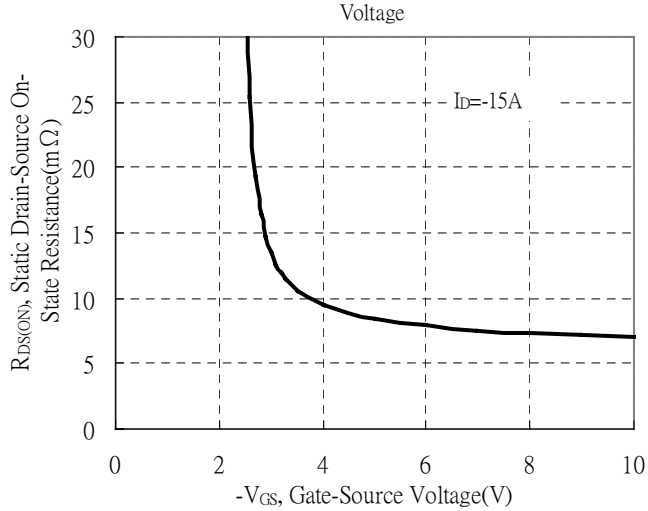
Static Drain-Source On-State resistance vs Drain Current



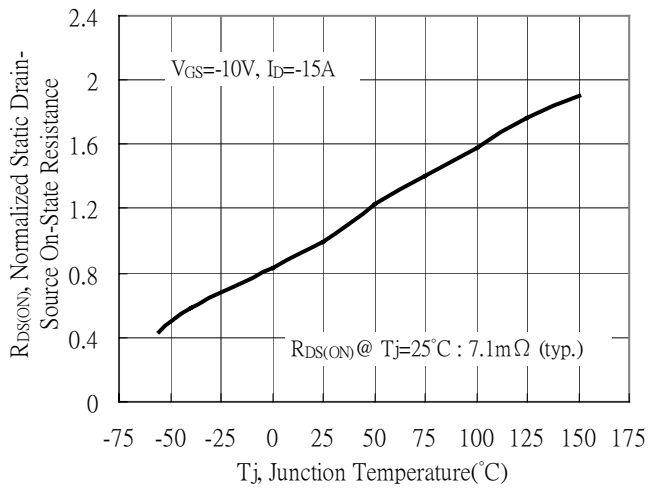
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

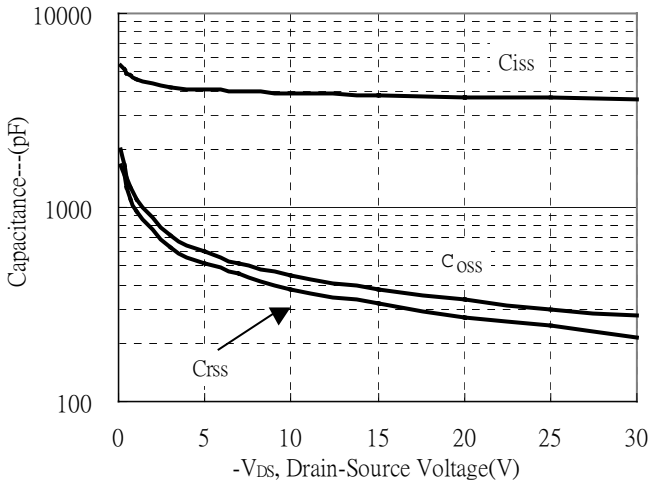


Drain-Source On-State Resistance vs Junction Tempearture

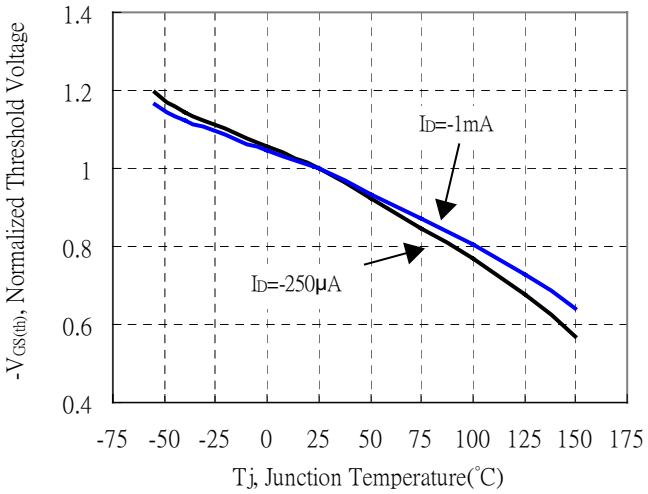


Typical Characteristics(Cont.)

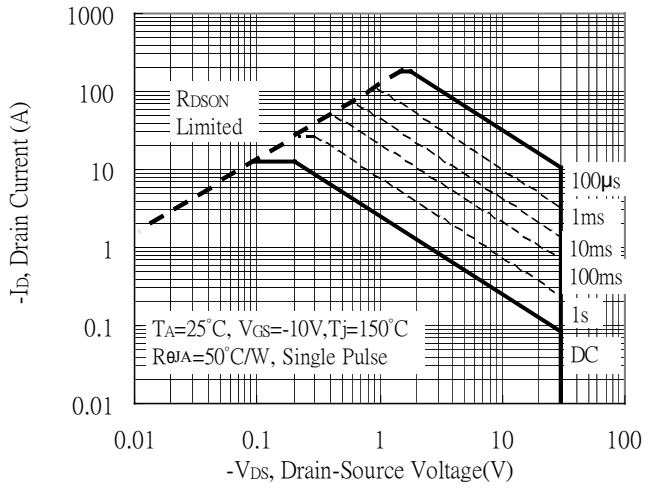
Capacitance vs Drain-to-Source Voltage



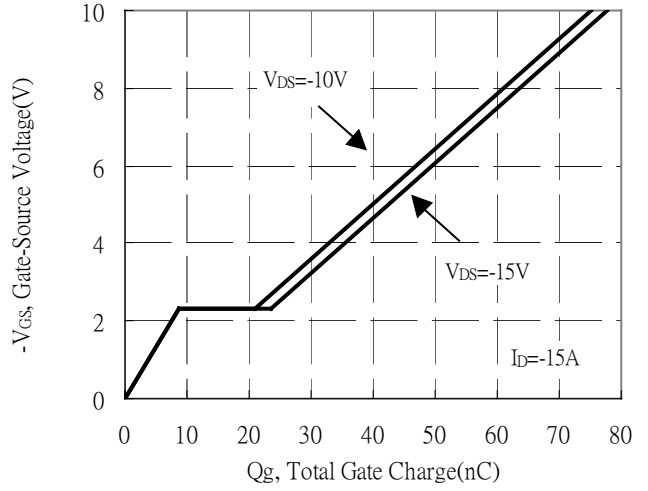
Threshold Voltage vs Junction Tempearture



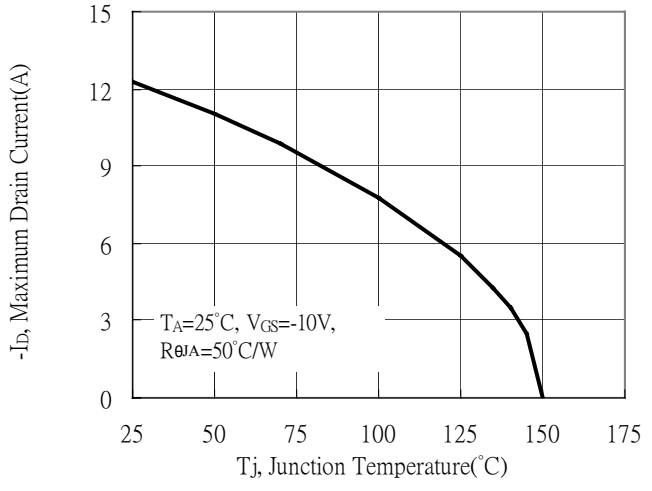
Maximum Safe Operating Area



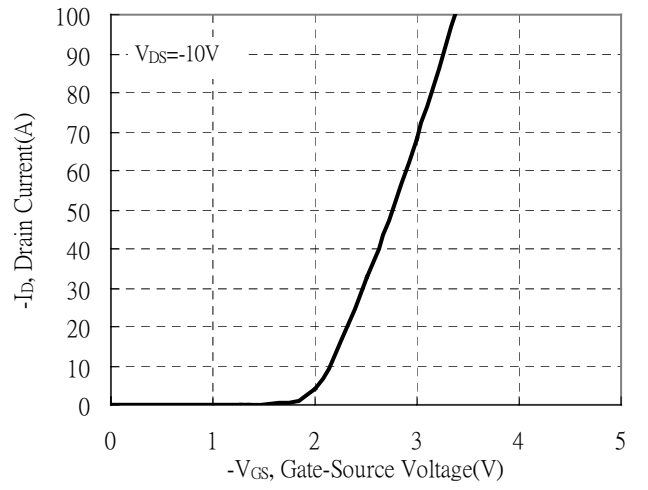
Gate Charge Characteristics



Maximum Drain Current vs Junction Temperature

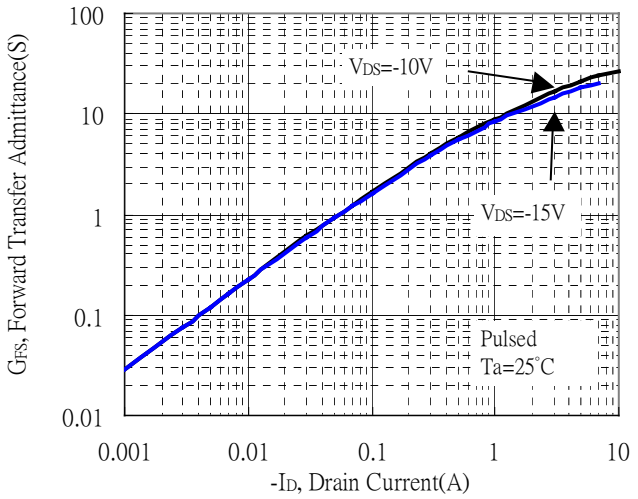


Typical Transfer Characteristics

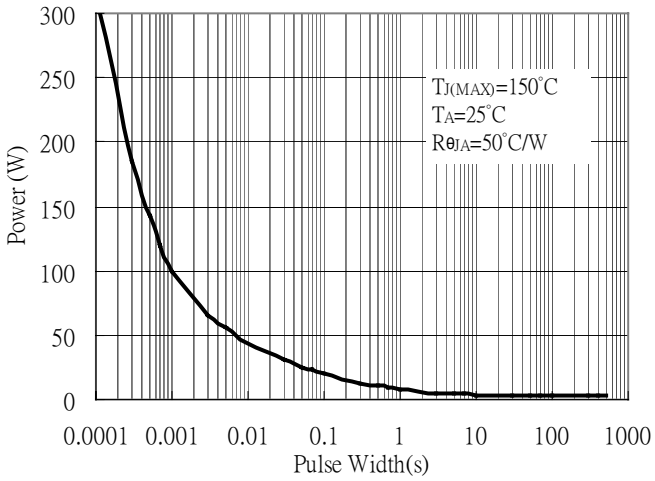


Typical Characteristics(Cont.)

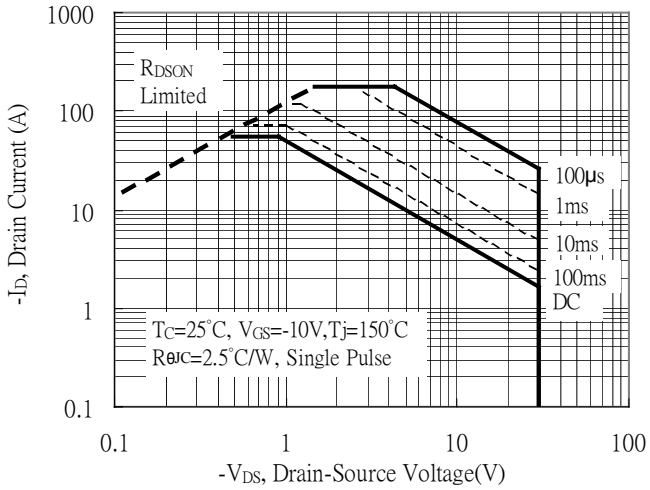
Forward Transfer Admittance vs Drain Current



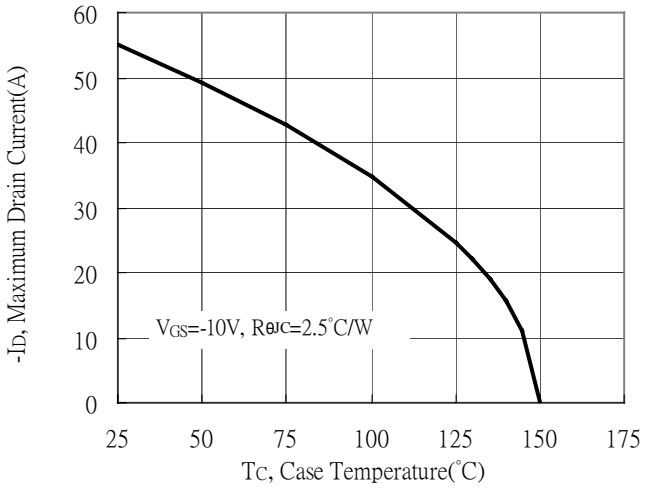
Single Pulse Maximum Power Dissipation



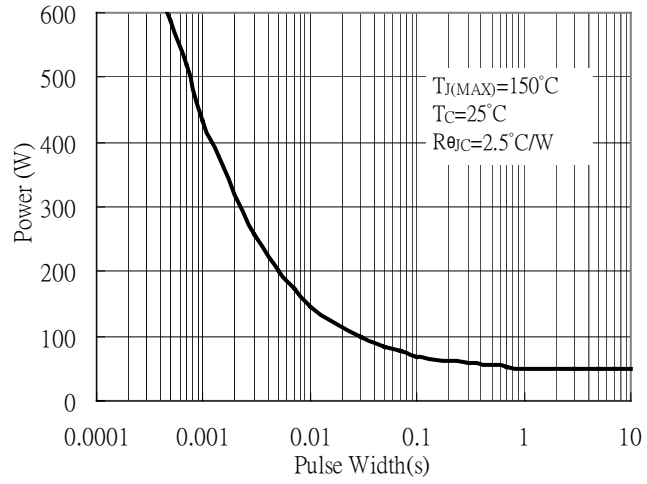
Maximum Safe Operating Area



Maximum Drain Current vs Case Temperature

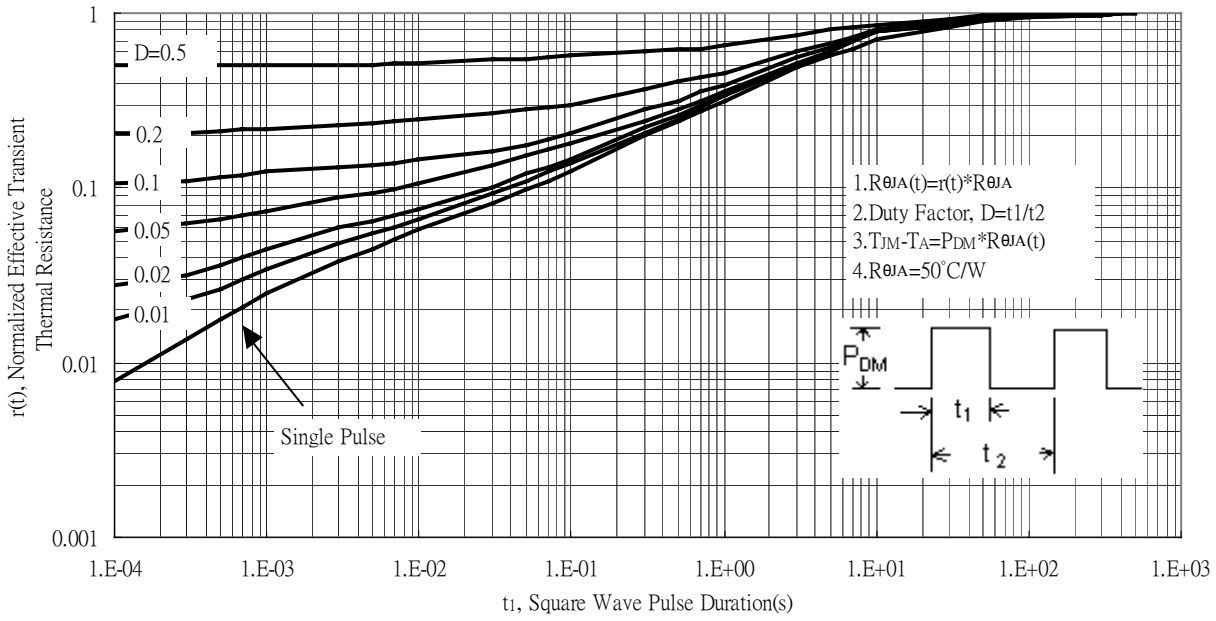


Single Pulse Maximum Power Dissipation

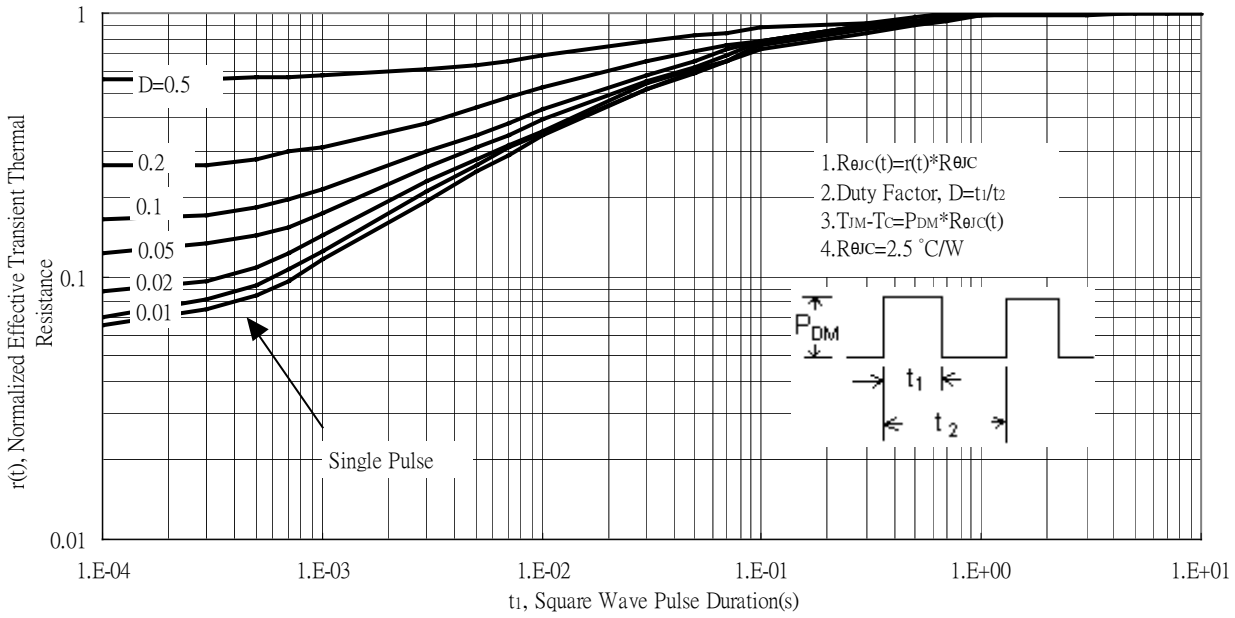


Typical Characteristics(Cont.)

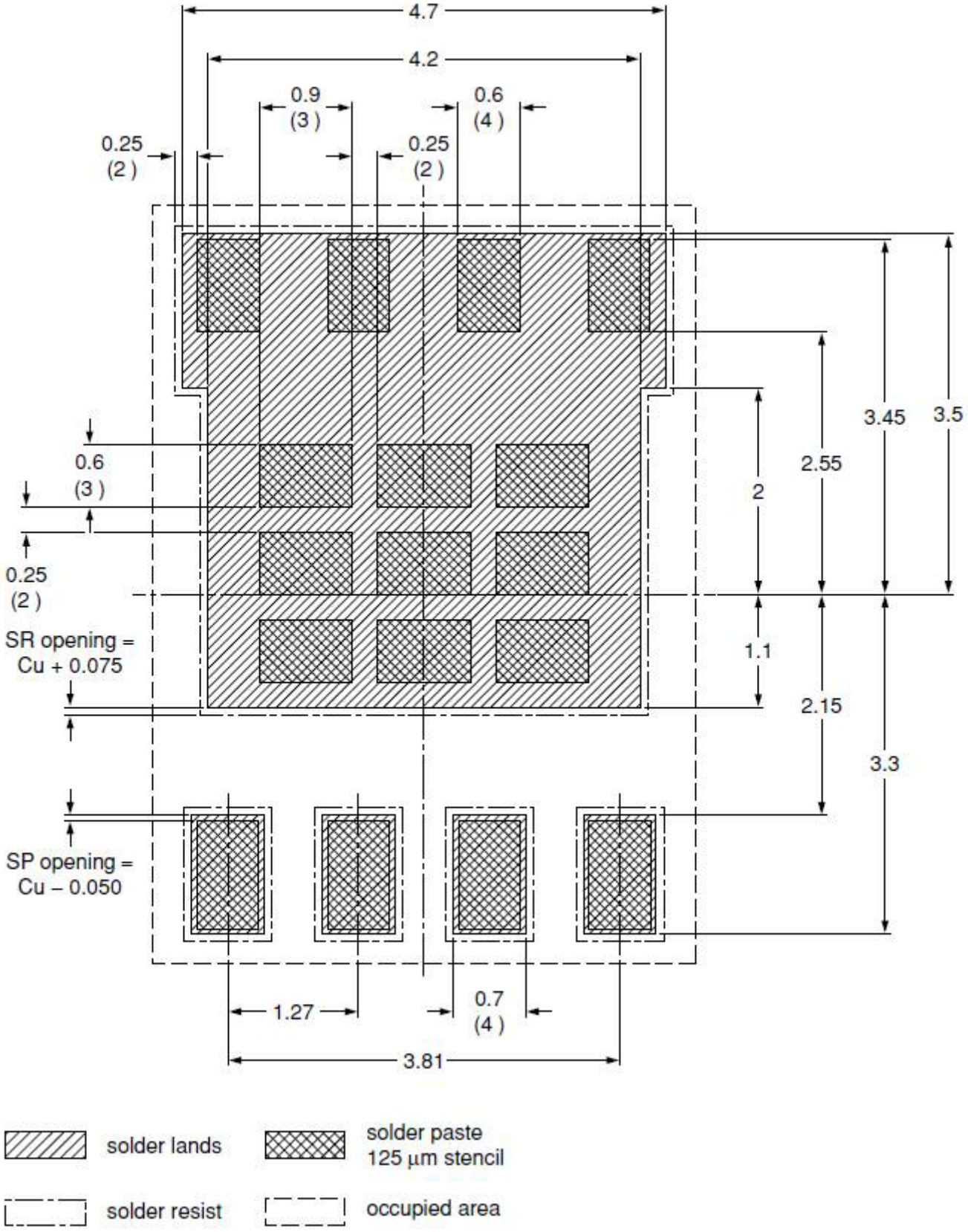
Transient Thermal Response Curves



Transient Thermal Response Curves

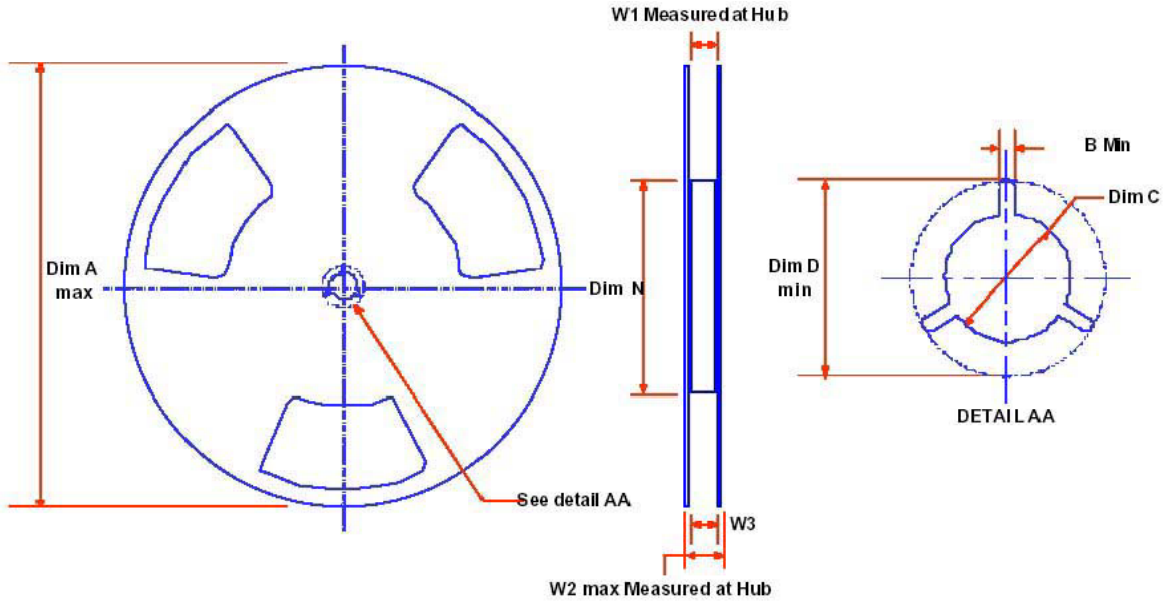


Recommended Soldering Footprint & Stencil Design



unit : mm

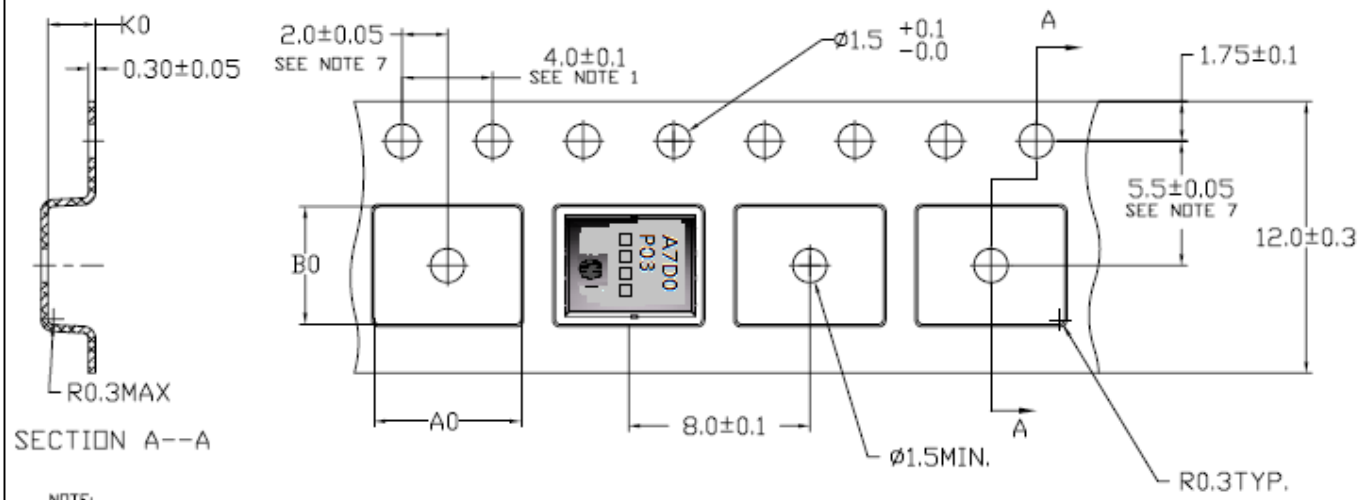
Reel Dimension



Dimensions are in inches and millimeters

Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
12mm	13" Dia (STD/L99Z)	13.00 330+/-1	0.059 1.5 Min.	0.512 13.0 Min.	0.795 20.2(ref.)	7.00 178+0/-2	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4(ref.)	0.469 – 0.606 11.9 – 15.4

Carrier Tape Dimension



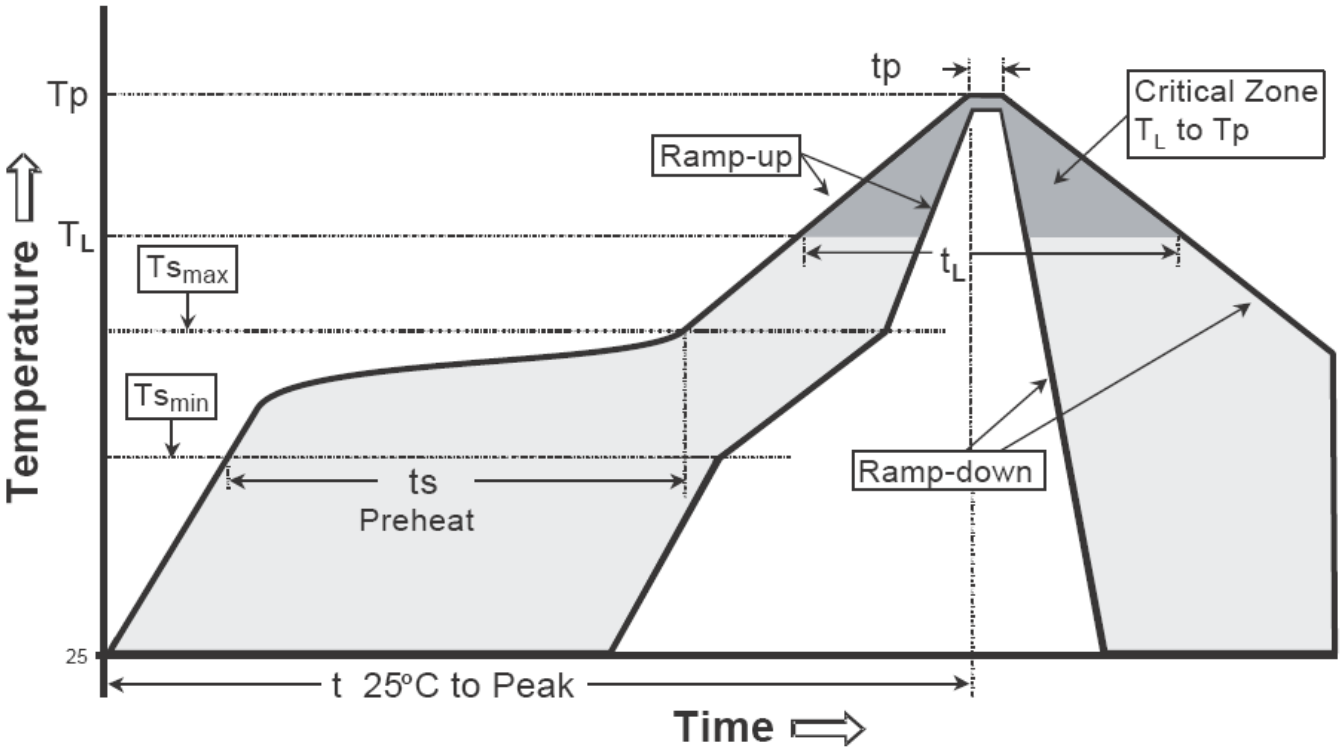
NOTE:
1. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE ±0.2
2. CAMBER NOT TO EXCEED 1mm IN 100mm, NONCUMULATIVE OVER 250mm.
3. MATERIAL: BLACK STATIC DISSIPATIVE PS.(POLYSTYRENE)
4. ALL DIMENSIONS ARE IN MILLIMETERS (UNLESS OTHERWISE SPECIFIED)
5. A0 AND B0 MEASURED ON A PLANE 0.3mm ABOVE THE BOTTOM OF THE POCKET
6. K0 MEASURED FROM A PLANE ON THE INSIDE BOTTOM OF THE POCKET TO THE TOP SURFACE OF THE CARRIER
7. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE
8. SURFACE RESISTIVITY
   1X10E4~1X10E11 OHMS/SQ
   1X10E4-1X10E6 OHMS/SQ. for Fairchild Only

A0=6.5±0.1
B0=5.3±0.1
K0=1.4±0.1

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

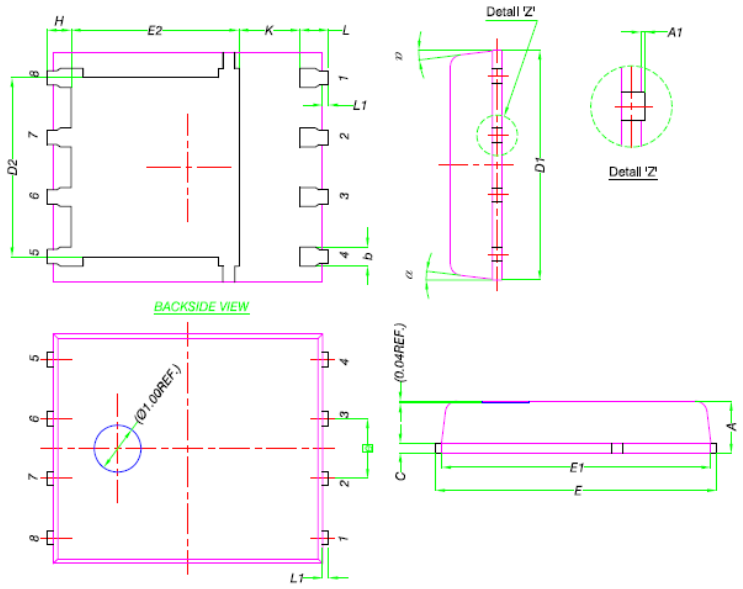
Recommended temperature profile for IR reflow

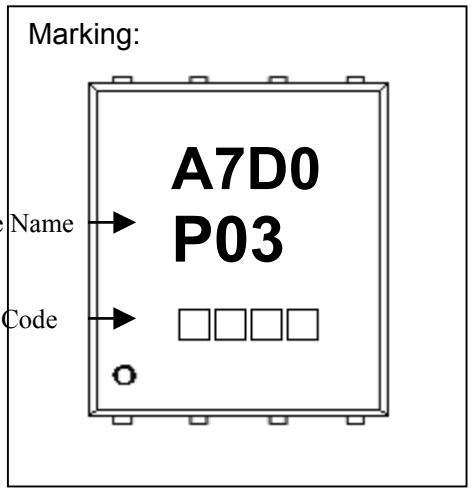


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(Ts min) −Temperature Max(Ts max) −Time(ts min to ts max)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (TL) − Time (tL)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note :1. All temperatures refer to topside of the package, measured on the package body surface.
2.For devices mounted on FR-4 PCB of 1.6mm or equivalent grade PCB. If other grade PCB is used, care should be taken to match the coefficients of thermal expansion between components and PCB. If they are not matched well, the solder joints may crack or the bodies of the parts may crack or shatter as the assembly cools.

DFN5x6 Dimension





8-Lead DFN5x6 Plastic Package
CYS Package Code : H8

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.90	1.10	0.035	0.043	E2	3.38	3.78	0.133	0.149
A1	0.00	0.05	0.000	0.002	e	1.27 BSC		0.050 BSC	
b	0.33	0.51	0.013	0.020	H	0.41	0.61	0.016	0.024
C	0.20	0.30	0.008	0.012	K	1.10	-	0.043	-
D1	4.80	5.00	0.189	0.197	L	0.51	0.71	0.020	0.028
D2	3.61	3.96	0.142	0.156	L1	0.06	0.20	0.002	0.008
E	5.90	6.10	0.232	0.240	θ	8°	12°	8°	12°
E1	5.70	5.80	0.224	0.228					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.